

LNPTM STAT-KONTM COMPOUND PX11002

PX11002

DESCRIPTION

LNP STAT-KON PX11002 compound is based on Nylon 6 resin containing conductive carbon powder. Added features of this grade include: Electrically Conductive, Impact Modified, Flame Retardant.

| GENERAL INFORMATION | |
|----------------------------|---|
| Features | Flame Retardant, Electrically Conductive, Impact resistant, No PFAS intentionally added |
| Fillers | Carbon Powder |
| Polymer Types | Polyamide 6 (Nylon 6) |
| Processing Techniques | Injection Molding |
| INDUSTRY | SUB INDUSTRY |
| Electrical and Electronics | Electronic Components |
| Industrial | Material Handling |

TYPICAL PROPERTY VALUES

Revision 20230607

| PROPERTIES | TYPICAL VALUES | UNITS | TEST METHODS |
|--|-----------------|------------|-------------------|
| MECHANICAL (1) | | | |
| Tensile Stress, yield, 5 mm/min | 42 | MPa | ISO 527 |
| Tensile Strain, break, 5 mm/min | 2.8 | % | ISO 527 |
| Tensile Modulus, 1 mm/min | 2400 | MPa | ISO 527 |
| Flexural Stress, yield, 2 mm/min | 68 | MPa | ISO 178 |
| Flexural Modulus, 2 mm/min | 2300 | MPa | ISO 178 |
| IMPACT (1) | | | |
| Multiaxial Impact | 20 | J | ISO 6603 |
| Izod Impact, unnotched 80*10*4 +23°C | 75 | kJ/m² | ISO 180/1U |
| Izod Impact, notched 80*10*4 +23°C | 10 | kJ/m² | ISO 180/1A |
| PHYSICAL (1) | | | |
| Melt Volume Rate | | | |
| Melt Volume Rate, MVR at 275°C/10.0 kg | 27 | cm³/10 min | ISO 1133 |
| Density | 1.31 | g/cm³ | ISO 1183 |
| ELECTRICAL (1) | | | |
| Surface Resistivity (2) | 1.E+04 – 1.E+10 | Ω | ASTM D257 |
| FLAME CHARACTERISTICS | | | |
| UL Compliant, 94V-1 Flame Class Rating (3) | 3 | mm | UL 94 by SABIC-IP |
| INJECTION MOLDING (4) | | | |
| Drying Temperature | 80 | °C | |
| Drying Time | 4 | Hrs | |
| Maximum Moisture Content | 0.15 - 0.25 | % | |
| Melt Temperature | 255 – 265 | °C | TDV TUAT MATTEDS |



| PROPERTIES | TYPICAL VALUES | UNITS | TEST METHODS |
|-----------------------------|----------------|-------|--------------|
| Front - Zone 3 Temperature | 250 – 260 | °C | |
| Middle - Zone 2 Temperature | 250 – 260 | °C | |
| Rear - Zone 1 Temperature | 245 – 255 | °C | |
| Mold Temperature | 55 – 95 | °C | |
| Back Pressure | 0.2 – 0.3 | MPa | |
| Screw Speed | 30 – 60 | rpm | |

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurement meets requirements as specified in ASTM D4496.
- (3) UL rating shown here is based on internal measurements.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

MORE INFORMATION

For curve data and CAE cards, please visit and register at https://materialfinder.sabic-specialties.com

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